

Critical Point Dryer for MEMS

CPD 408

BAL-TEC DI CPD 408

21°C Bbar

CLOSE START

Critical point dryer for Чъ Б and B inch wafers for MEMS.

> Coating Cryo Preparation Ion Etching Solid State Preparation Accessories and more...

KEY FEATURES INCLUDE:

- safe and easy operation
- gentle substrate treatment
- clean room compatible
- compact bench unit
- economical operation
- excellent visual access

Critical Point Dryer for MEMS





Your economical solution for critical point drying of MEMS.



MORE FEATURES

Compact bench unit

Space saving design with separate cooling/heating unit.

Economical

Minimum consumption of the CO₂ transitional fluid because of integrated refrigerator (no cooling agent required) and unique double chamber system.

Easy substrate loading

The top loading system with wafer carrier and a safety sliding cover is ideal for fast, easy substrate insertion.

Easy operation

The solenoid high pressure valves, the heating and cooling are operated fully automated from the touchpad keyboard (no difficult-to-use manual valves). Start – Stop operation is programmed.

Guaranteed personnel safety

Approved pressure container with bursting membrane and pressure relieve valve and other independent safety features guarantee absolute safe operation.

Gentle substrate treatment

Damaging turbulences caused by admitting and draining fluids too fast are reduced to a minimum through the use of apertures.

Automatic cooling / heating system

The cooling / heating system eliminates the need for other external supplies such as CO₂ cooling.

Substrate cleaning and drying steps

Chemical etching Washing Dehydration Transfer to drying medium Drying Next steps Etching acid Isopropanol CO2 CP Drying Washing solution Acetone CO2 CP Drying Normal pressure High pressure Normal pressure

Conveniently arranged

Digital temperature and

pressure displays and a

Universal application

The variable operating

parameters and the EPDM

Consistent modular design

and removable cover panels

assure easy access to the individual assemblies.

commonly used transitional flu-

and Teflon seals allow all

ids to be used.

Service friendly

status of the unit.

mimic diagram to indicate

the momentary operational

control and display elements

Unique double chamber system for easy loading and low CO2 consumption.





THE CRITICAL POINT DRYING METHOD

Drying micro electro mechanical systems (MEMS) in air or under vacuum can drastically alter their structures or even destroy them completely. They must therefore be dried by a gentlier method. One well-known method is "Critical Point Drying".

Phase diagram



K= Critical Point A= Initial state E =Final state T=Triple point ① Air-drying / vacuum-drying ② Critical point drying The surface tension of the water, isopropanol or acetone in a micro device at the point at which it changes from the liquid phase to the gaseous phase ① can destroy the device through capillary forces (e.g. membrane). By increasing the pressure and temperature of the substrate it is possible to dry it without crossing a phase boundary ②. This is possible because once the critical point has been passed, the density of the "liquid" and the density of the "gas" are the same. The critical point for water is 228.5bar and 374°C. However, this high pressure and extreme temperature would normally destroy a substrate. For this reason the substrate must be treated in a suitable transitional fluid such as CO₂ whose critical point of 73.8bar and 31°C is considerably more advantageous.

TECHNICAL DATA

Dimensions570 x 600 x 330mmCPD 408
Usable volume
Fluid fillingØ 205mm x 15mm
approx. 500mlWeight CPD 408 Basic System
Weight Cooling/Heating- Systemapprox. 65kg
approx. 70kgConnection data
Electrical:
Voltage
Frequency
Power consumption
Main fuse F1 / F2230V / 240V / 115V
50 / 60Hz
1000VA
SA slow blowing (230V / 240V)
8A slow blowing (115V)Transitional fluid:
Inlet
OutletM12 x 1.5
Ø 6mm (R1/8")Highest permissible pressure
Safety bursting membraneapprox. 150bar

Operating parameters

Cycle time approx. 20min

Simple one button operation from start to stop with preset parameters.



SPECIFICATION

1. Housing

Console housing containing the pressure chamber, inlet and outlet system for the preparation fluids. A separate cooling/heating system also contains the power supply. The connections for the preparation fluids inlet/outlet are located on the back of the unit. **Dimensions**

The CPD is 550mm wide, 450mm deep, 350mm high and fit in a standard flow hood. The cooling/heating unit can be installed in the grey room. It is 450mm wide, 800mm deep and 550mm high.

2. Pressure chamber

The pressure chamber is made of Aluminum with safety bolted door, integrated cooling pipes and integrated inlet and outlet ports for cleaning fluids.

3. Cleaning fluid inlet/outlet system

Inlet (M12 x 1.5), outlet (Ø 6mm) are located on the back panel.



4. Cooling/Heating System The water cooling/heating system is designed to cool the pressure chamber in the range from +8°C to +12°C and heat it to +35°C to +45°C .

5. Power supply and control unit

The power supply consists of a 24VDC power supply card and the microprocessor unit. Both parts are integrated in the CPD 408. The touch panel in the front is connected to the microprocessor to display and control all functions of the CPD.

Compact bench unit fits in a standard flow hood.



ORDERING INFORMATION CPD 408 basic unit per specification item 1-7.

CPD 408 wafers 230VAC 50/60Hz 115VAC 50/60Hz Order No. CPD 408 EVN CPD 408 UVN

6. Safety devices

The safety devices consist of the following:

- Tested substrate pressure chamber (min. 150bar)
- Safety pressure relieve valve
- Bursting membrane (responds at 150bar)
- Precisely dimensioned heating system
- Safety screw-on cover
- Software controlled overpressure relieve valves

7. Wafer transfer container

For transferring wafers submerged in transitional fluid to the pressure chamber in the critical point dryer. With mechanism for draining and rinsing the container.

The wafer container holds 1 wafer. Other transfer container kits for wafer pieces are available on request.



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